

# S3AF THRU S3MF

## SURFACE MOUNT GENERAL PURPOSE SILICON RECTIFIER

Reverse Voltage – 50 to 1000 V

Forward Current – 3 A

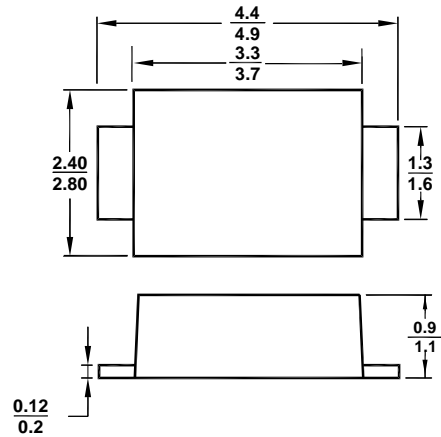
SMAF

### Features

- Glass Passivated Chip Junction
- For surface mount applications
- Low profile package
- Easy pick and place

### Mechanical Data

- **Case:** SMAF
- **Terminals:** Solderable per MIL-STD-750, method 2026



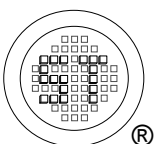
All Dimensions in mm

### Maximum Ratings and Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20%.

| Parameter  | Symbols         | S3AF          | S3BF | S3DF | S3GF | S3JF | S3KF | S3MF | Units              |
|--|-----------------|---------------|------|------|------|------|------|------|--------------------|
|  | Marking         | S3A           | S3B  | S3D  | S3G  | S3J  | S3K  | S3M  | -                  |
| Maximum Repetitive Peak Reverse Voltage  | $V_{RRM}$       | 50            | 100  | 200  | 400  | 600  | 800  | 1000 | V                  |
| Maximum RMS Voltage  | $V_{RMS}$       | 35            | 70   | 140  | 280  | 420  | 560  | 700  | V                  |
| Maximum DC Blocking Voltage  | $V_{DC}$        | 50            | 100  | 200  | 400  | 600  | 800  | 1000 | V                  |
| Maximum Average Forward Rectified Current at $T_a = 65^\circ\text{C}$  | $I_{F(AV)}$     | 3             |      |      |      |      |      |      | A                  |
| Peak Forward Surge Current 8.3 ms Single Half Sine-wave Superimposed on Rated Load (JEDEC Method)                | $I_{FSM}$       | 100           |      |      |      |      |      |      | A                  |
| Maximum Forward Voltage at 3 A   | $V_F$           | 1.2           |      |      |      |      |      |      | V                  |
| Maximum DC Reverse Current at Rated DC Blocking Voltage<br>$T_a = 25^\circ\text{C}$<br>$T_a = 125^\circ\text{C}$ | $I_R$           | 5<br>250      |      |      |      |      |      |      | $\mu\text{A}$      |
| Typical Junction Capacitance at $V_R = 4\text{ V}$ , $f = 1\text{ MHz}$  | $C_J$           | 53            |      |      |      |      |      |      | pF                 |
| Typical Thermal Resistance <sup>1)</sup>   | $R_{\theta JA}$ | 13<br>47      |      |      |      |      |      |      | $^\circ\text{C/W}$ |
| Operating and Storage Temperature Range  | $T_j, T_{stg}$  | - 55 to + 150 |      |      |      |      |      |      | $^\circ\text{C}$   |

<sup>1)</sup> P.C.B. mounted with 0.2 X 0.2" ( 5 X 5 mm) copper pad areas.

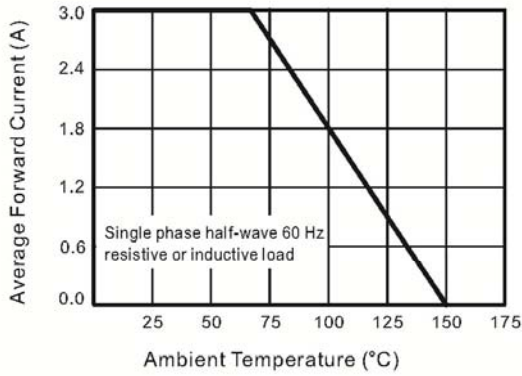


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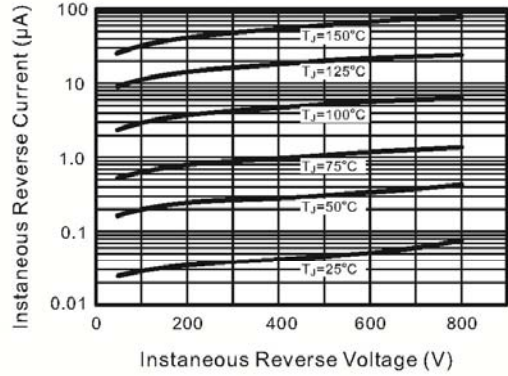


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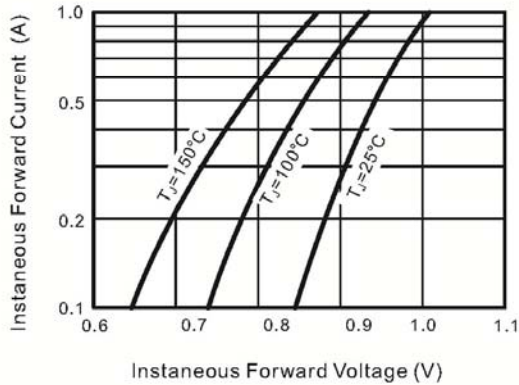
Forward Current Derating Curve



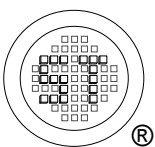
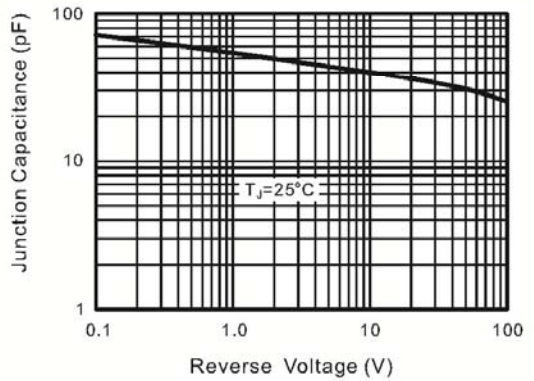
Typical Instaneous Reverse Characteristics



Typical Forward Characteristic



Typical Junction Capacitance



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